

PROCESS AND APPARATUS FOR DISENGAGING SEMICONDUCTOR  
DIE FROM AN ADHESIVE FILM

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ABSTRACT OF THE DISCLOSURE

An apparatus and method for separating a semiconductor die (303) from  
an adhesive tape (32) are disclosed. The apparatus includes a blade (34)  
mechanically coupled to a blade holder (36), wherein the blade (34) is inclined  
10 relative to the primary surface of the semiconductor die (303). The method  
further comprises lifting the semiconductor die (303) while it is attached to the  
adhesive tape (32) to assist disengagement. The blade (34) facilitates peeling of  
the semiconductor die (303) from the adhesive tape (32) while distributing  
stress exerted on the semiconductor die (303) over a larger surface area  
15 resulting in reduced die fractures (20).

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